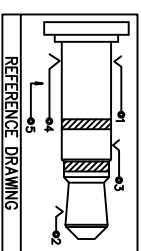
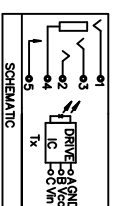
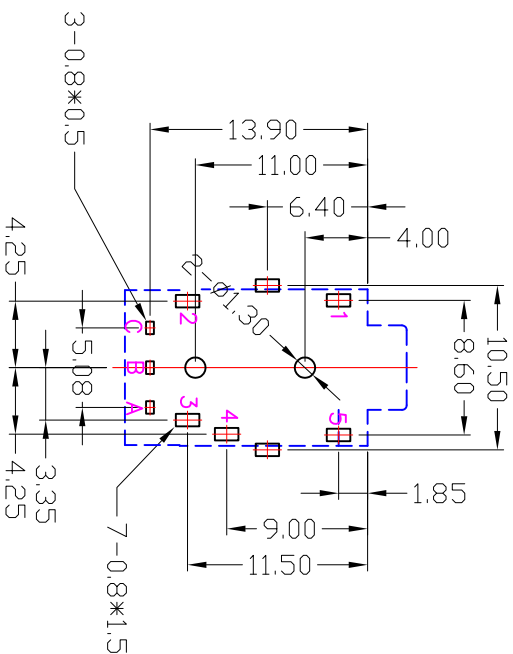
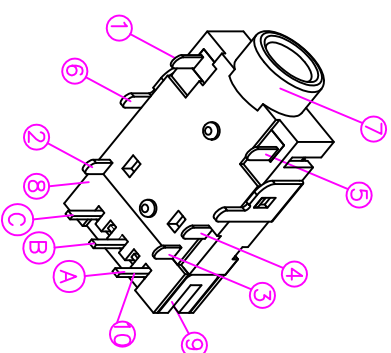
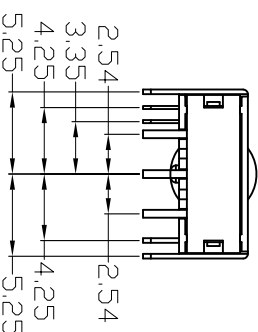
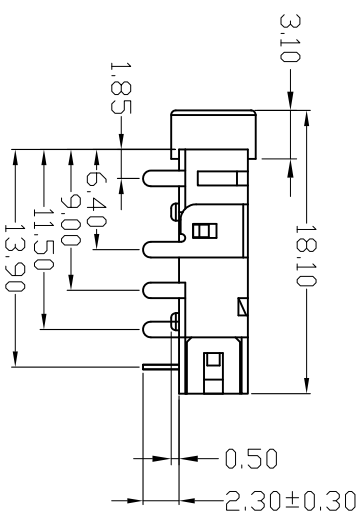
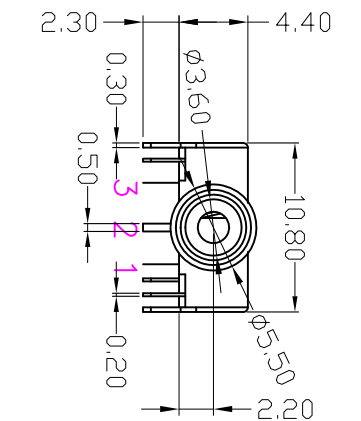
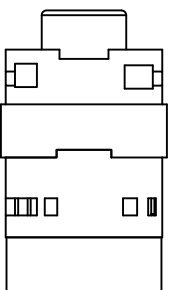


REV	DATE	DESCRIPTION



基板下參考圖(公差±0.3)  
PCB LAYOUT(Tol.±0.3)

ITEM	DESCRIPTIONS	MATERIAL	FINISH	Q'TY	NOTE
⑩	DRIVE IC(TX)			1	
⑨	COVER	HIGH-TEMP PLASTIC	BLACK	1	
⑧	CASE	HIGH-TEMP PLASTIC	BLACK	1	
⑦	HOUSING	HIGH-TEMP PLASTIC	BLACK	1	
⑥	SHIELDING	COPPER ALLOY	NI	1	60u"min
⑤	DETECTOR	PHOSPHOR BRONZE	Au	1	
④	GND	PHOSPHOR BRONZE	Au	1	Au 1u" &
③	RIGHT CHANNEL	PHOSPHOR BRONZE	Au	1	NI 50u" min
②	LEFT CHANNEL	PHOSPHOR BRONZE	Au	1	
①	DETECTOR	PHOSPHOR BRONZE	Au	1	

PART NAME	光纤连接器
PART NUMBER	DLT11M1
TOLERANCE	±0.20
APPROVED	
CHECK	
DRAWING	Bunny
UNIT	mm
MATERIAL	
SCALE	
FIT	
DATE	2011/03/01
PAGE	1/1

# XYFWCN

Third Angle Projection